

# Gap Pad<sup>®</sup> 1500S30 (AKA Project Madrid)

Highly Conformable, Thermally Conductive, Reinforced “S-Class” Gap Filling Material

## Features and Benefits

- Thermal Conductivity: 1.3 W/m-K
- Highly conformable/low hardness
- Designed for low-stress applications
- Fiberglass reinforced for puncture, shear and tear resistance

Gap Pad<sup>®</sup> 1500S30 is a highly compliant Gap Pad<sup>®</sup> that is ideal for fragile or low-stress applications. The material is fiberglass reinforced for improved puncture resistance and handling characteristics. Gap Pad<sup>®</sup> 1500S30 maintains a conformable, yet elastic nature that provides excellent interfacing and wet-out characteristics, even to surfaces with high roughness or uneven topography.

Gap Pad<sup>®</sup> 1500S30 has inherent tack on both sides of the material, eliminating the need for thermally impeding adhesive layers.

Please contact your local Bergquist Sales Representative for Sample Inquiries and additional product information.

## TYPICAL PROPERTIES OF GAP PAD<sup>®</sup> 1500S30

Property	Imperial Value	Metric Value	Test Method
Color	Light Pink	Light Pink	Visual
Reinforcement Carrier	Fiberglass	Fiberglass	-
Thickness (inch) / (mm)	0.020 to 0.125	0.508 to 3.175	ASTM D374
Inherent Surface Tack (1- or 2-sided)	2	2	-
Density (g/cc)	1.8	1.8	ASTM D792
Heat Capacity (J/g-K)	1.0	1.0	ASTM E1269
Hardness, Bulk Rubber (Shore 00) (1)	30	30	ASTM D2240
Young's Modulus (psi) / (kPa) (2)	16	110	ASTM D575
Continuous Use Temp. (°C)	-76 to 392	-60 to 200	-
<b>Electrical</b>			
Dielectric Breakdown Voltage (Vac)	>6000	>6000	ASTM D149
Dielectric Constant (1 Mhz)	5	5	ASTM D150
Volume Resistivity, (Ohm-m)	10 <sup>9</sup>	10 <sup>9</sup>	ASTM D257
Flame Rating	V-O	V-O	U.L. 94
<b>Thermal</b>			
Thermal Conductivity (W/m-K)	1.3	1.3	ASTM D5470
1) Thirty second delay value Shore 00 hardness scale.			
2) Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch <sup>2</sup> . For more information on Gap Pad modulus, refer to Bergquist Application Note #116.			

## Typical Applications

- Low Pressure Applications
- Computer and peripherals
- Telecommunications
- Between any heat-generating semiconductor and a heat sink

## Configurations Available

- Sheet form and die-cut parts

Beta Data Sheet  
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